

N-channel SiC power MOSFET

V_{DSS}	1700V
R _{DS(on)} (Typ.)	1.15Ω
I _D	3.7A
P_D	35W

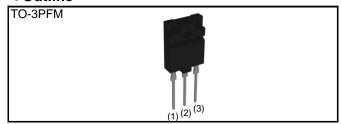
Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Long creepage distance
- 4) Simple to drive
- 5) Pb-free lead plating; RoHS compliant

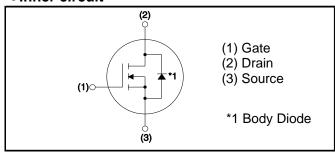
Application

- · Auxilialy power supplies
- · Switch mode power supplies

Outline



•Inner circuit



Packaging specifications

	Packaging	Tube
R	Reel size (mm)	-
Typo	Tape width (mm)	-
Туре	Basic ordering unit (pcs)	30
	Taping code	-
	Marking	SCT2H12NZ

● Absolute maximum ratings (Ta = 25°C)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V_{DSS}	1700	V
Continuous drain surrent	T _c = 25°C	I _D *1	3.7	А
Continuous drain current	T _c = 100°C	I _D *1	2.6	А
Pulsed drain current		I _{D,pulse} *2	9.2	А
Gate - Source voltage (DC)		V _{GSS}	-6 to 22	V
Gate - Source surge voltage (T _{surge} < 300nsec)		V _{GSS-surge} *3	-10 to 26	V
Power dissipation (T _c = 25°C)		P _D	35	W
Junction temperature		T _j	175	°C
Range of storage temperature		T _{stg}	-55 to +175	°C

●Thermal resistance

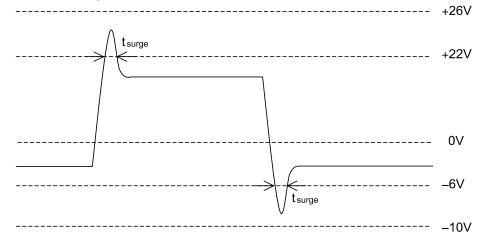
Parameter	Symbol	Values			Unit
- Farameter	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	R_{thJC}	-	3.32	4.32	°C/W
Thermal resistance, junction - ambient	R_{thJA}	-	36.8	50	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

●Electrical characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit	
raiailletei	Symbol	Conditions	Min.	Тур.	Max.	Utill	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$, $I_D = 1mA$	1700	1	ı	V	
		$V_{DS} = 1700V, V_{GS} = 0V$					
Zero gate voltage drain current	I _{DSS}	$T_j = 25^{\circ}C$	-	0.1	10	μΑ	
		T _j = 150°C	-	0.2	-		
Gate - Source leakage current	I _{GSS+}	$V_{GS} = +22V, V_{DS} = 0V$	-	-	100	nA	
Gate - Source leakage current	I_{GSS-}	$V_{GS} = -6V, V_{DS} = 0V$	1	-	-100	nA	
Gate threshold voltage	V _{GS (th)}	$V_{DS} = V_{GS}$, $I_D = 0.9 \text{mA}$	1.6	2.8	4.0	V	

^{*1} Limited only by maximum temperature allowed.

^{*3} Example of acceptable Vgs waveform



*4 Pulsed

^{*2} PW \leq 10 μ s, Duty cycle \leq 1%

•Electrical characteristics $(T_a = 25^{\circ}C)$

Doromotor	Symbol Conditions –		Values			l loit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
		$V_{GS} = 18V, I_D = 1.1A$				
Static drain - source on - state resistance	R _{DS(on)} *4	T _j = 25°C	-	1.15	1.5	Ω
on class resistance		T _j = 125°C	-	1.71	-	
Gate input resistance	R_{G}	f = 1MHz, open drain	-	64	-	Ω
Transconductance	g _{fs} *4	$V_{DS} = 10V, I_D = 1.1A$	-	0.4	-	S
Input capacitance	C _{iss}	$V_{GS} = 0V$	-	184	-	
Output capacitance	C _{oss}	V _{DS} = 800V	-	16	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	6	-	
Effective output capacitance, energy related	C _{o(er)}	$V_{GS} = 0V$ $V_{DS} = 0V$ to 800V	-	17	-	pF
Turn - on delay time	t _{d(on)} *4	$V_{DD} = 500V, I_D = 1.1A$	-	16	-	
Rise time	t _r *4	$V_{GS} = 18V/0V$	-	21	-	
Turn - off delay time	t _{d(off)} *4	$R_L = 455\Omega$	-	35	-	ns
Fall time	t _f *4	$R_G = 0\Omega$	-	74	-	
Turn - on switching loss	E _{on} *4	$V_{DD} = 800V, I_{D} = 1.1A$ $V_{GS} = 18V/0V$	-	57	-	1
Turn - off switching loss	E _{off} *4	$R_G = 0\Omega$, L=2mH * E_{on} includes diode reverse recovery	-	32	-	μJ

●Gate Charge characteristics (T_a = 25°C)

Parameter	Symbol	Conditions		Values		Unit
raiametei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	Qg *4	V _{DD} = 500V	-	14	ı	
Gate - Source charge	Q _{gs} *4	I _D =1A	-	4	-	nC
Gate - Drain charge	Q _{gd} *4	V _{GS} = 18V	-	5	-	
Gate plateau voltage	V _(plateau)	$V_{DD} = 500V, I_D = 1A$	-	10.5	-	V

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
raiainetei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Inverse diode continuous, forward current	l _S *1	T _c = 25°C	1	1	4	А
Inverse diode direct current, pulsed	I _{SM} *2	11 _c = 25 C	-	-	10	А
Forward voltage	V _{SD} *4	$V_{GS} = 0V, I_{S} = 1.1A$	-	4.3	-	V
Reverse recovery time	t _{rr} *4		-	21	-	ns
Reverse recovery charge	Q _{rr} *4	I _F = 1.1A, V _R = 800V di/dt = 300A/μs	-	13	-	nC
Peak reverse recovery current	I _{rrm} *4		-	1.1	-	Α

● Typical Transient Thermal Characteristics

Symbol	Value	Unit
R _{th1}	816m	
R _{th2}	1939m	K/W
R _{th3}	567m	

Symbol	Value	Unit
C_{th1}	127μ	
C _{th2}	1.64m	Ws/K
C _{th3}		

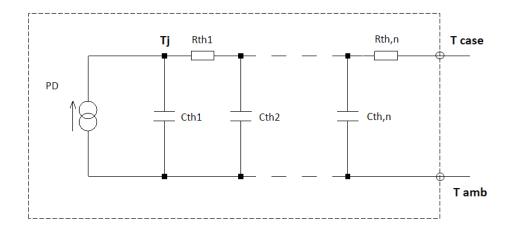
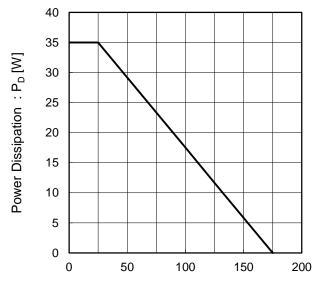
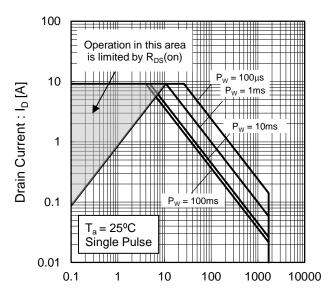


Fig.1 Power Dissipation Derating Curve



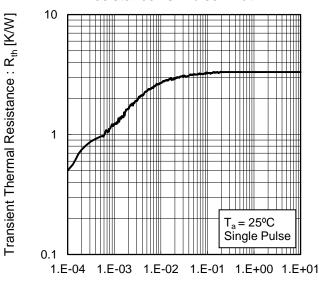
Junction Temperature : T_i [°C]

Fig.2 Maximum Safe Operating Area



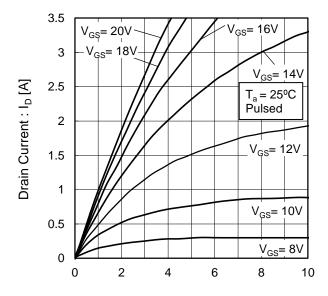
Drain - Source Voltage : V_{DS} [V]

Fig.3 Typical Transient Thermal Resistance vs. Pulse Width



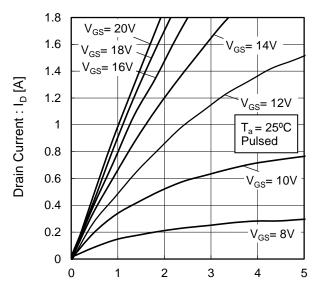
Pulse Width : P_W [s]

Fig.4 Typical Output Characteristics(I)

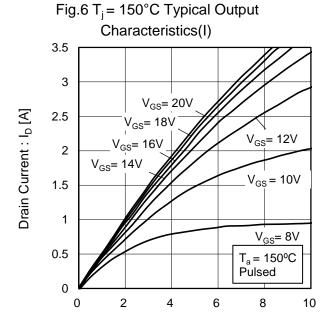


Drain - Source Voltage : V_{DS} [V]

Fig.5 Typical Output Characteristics(II)



Drain - Source Voltage : V_{DS} [V]



Drain - Source Voltage: V_{DS} [V]

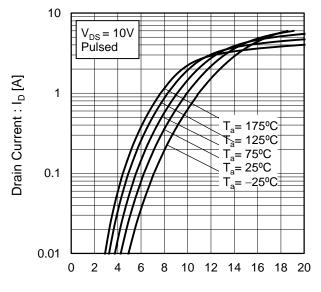
1.8 V_{GS}= 20V 1.6 $V_{GS} = 18V$ 1.4 V_{GS}= 16V Drain Current : I_D [A] $V_{GS} = 14V$ 1.2 $V_{GS} = 12V$ $V_{GS} = 10V$ 1 8.0 $V_{GS} = 8V$ 0.6 0.4 $T_a = 150^{\circ}C$ 0.2 Pulsed 0 2 0 1 3

Fig.7 $T_i = 150$ °C Typical Output

Characteristics(II)

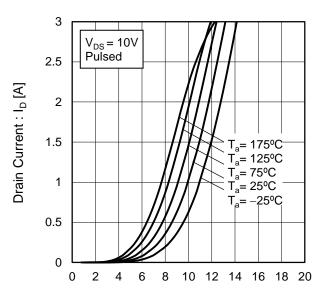
Drain - Source Voltage : V_{DS} [V]

Fig.8 Typical Transfer Characteristics (I)



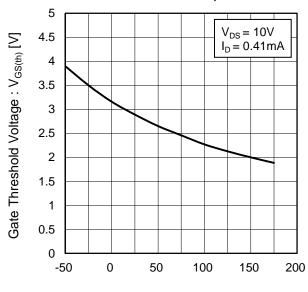
Gate - Source Voltage : V_{GS} [V]

Fig.9 Typical Transfer Characteristics (II)



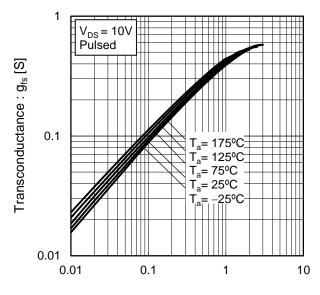
Gate - Source Voltage : V_{GS} [V]

Fig.10 Gate Threshold Voltage vs. Junction Temperature



Junction Temperature : T_j [°C]

Fig.11 Transconductance vs. Drain Current



Drain Current : I_D [A]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

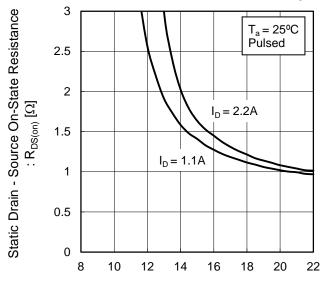
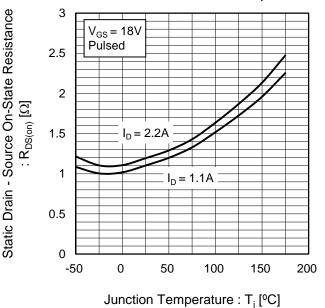
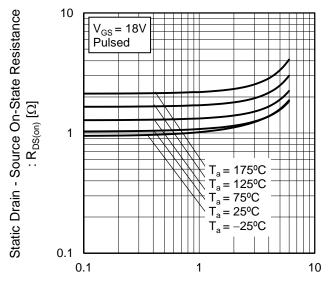


Fig.13 Static Drain - Source On - State
Resistance vs. Junction Temperature



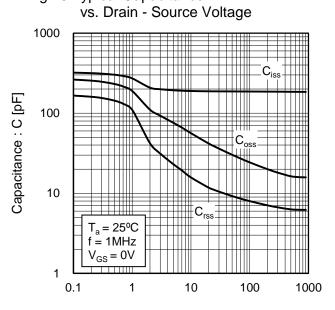
Gate - Source Voltage : V_{GS} [V]

Fig.14 Static Drain - Source On - State Resistance vs. Drain Current



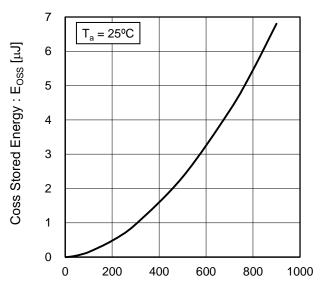
Drain Current: I_D [A]

Fig.15 Typical Capacitance



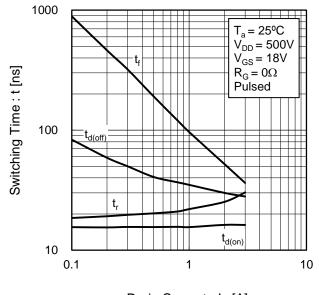
Drain - Source Voltage : V_{DS} [V]

Fig.16 Coss Stored Energy



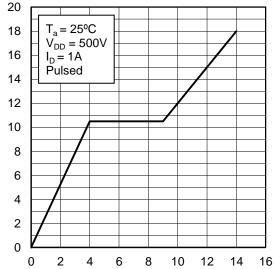
Drain - Source Voltage : V_{DS} [V]

Fig.17 Switching Characteristics



Drain Current : I_D [A]

Fig.18 Dynamic Input Characteristics



Total Gate Charge : Q_g [nC]

Gate - Source Voltage: V_{GS} [V]

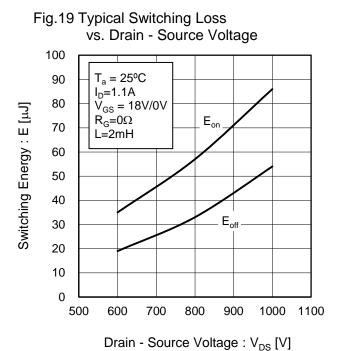
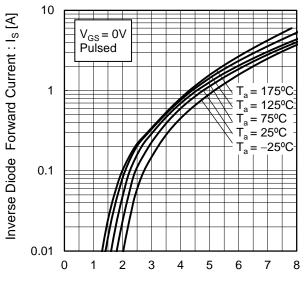


Fig.20 Typical Switching Loss vs. Drain Current 250 $T_a = 25^{\circ}C$ V_{DD}=800V $V_{GS} = 18V/0V$ $R_{G} = 0\Omega$ L = 2mH200 Switching Energy : E [µJ] 150 100 $\mathsf{E}_{\mathsf{off}}$ 50 0 2 3 4 5 0 Drain Current : I_D [A]

Fig.21 Typical Switching Loss vs. External Gate Resistance 140 $T_a = 25^{\circ}C$ V_{DD}=800V 120 E_{on} $I_{D} = 1.1A$ Switching Energy : E $[\mu J]$ $V_{GS} = 18V/0V$ 100 L=2mH 80 60 $\mathsf{E}_{\mathsf{off}}$ 40 20 0 0 20 40 60 100 80 External Gate Resistance : $R_G[\Omega]$

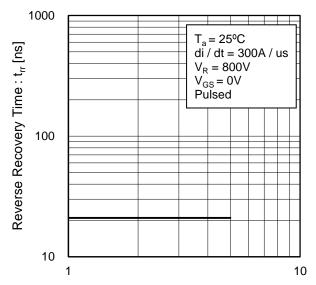
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Fig.22 Inverse Diode Forward Current vs. Source - Drain Voltage



Source - Drain Voltage : V_{SD} [V]

Fig.23 Reverse Recovery Time vs.Inverse Diode Forward Current



Inverse Diode Forward Current : I_S [A]

●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

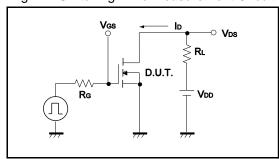


Fig.2-1 Gate Charge Measurement Circuit

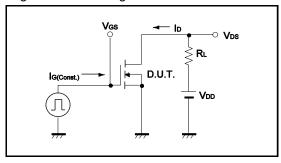


Fig.3-1 Switching Energy Measurement Circuit

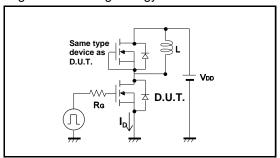


Fig.4-1 Reverse Recovery Time Measurement Circuit Fig.4-2 Reverse Recovery Waveform

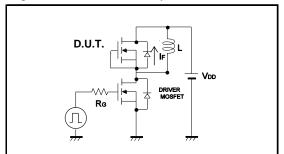


Fig.1-2 Switching Waveforms

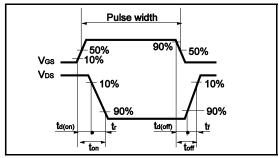


Fig.2-2 Gate Charge Waveform

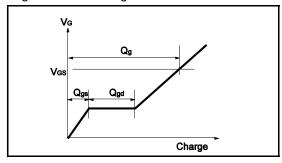
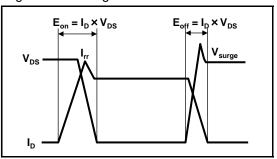
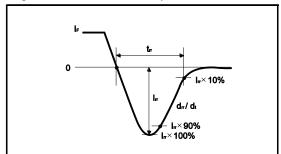


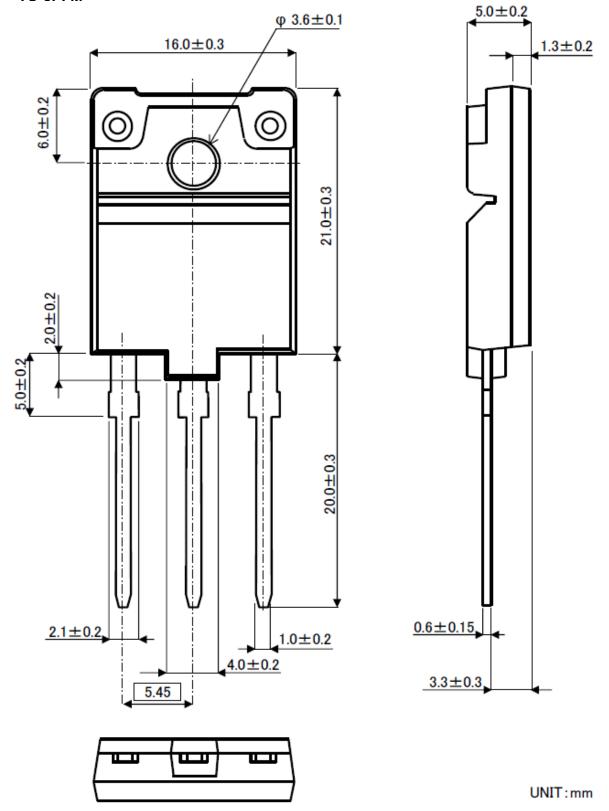
Fig.3-2 Switching Waveforms





●Dimensions (Unit : mm)





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